Specification of Thermoelectric Module

TEC1-26318

Description

The 263 couples, 50 mm \times 50 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

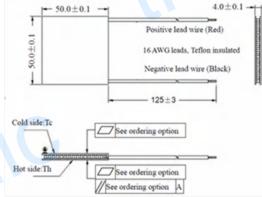
Performance Specification Sheet

Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Th(°C)	27	50	Hot side temperature at environment: dry air, N ₂		
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side		
U _{max} (Voltage)	32.6	35.2	Voltage applied to the module at DT _{max}		
I _{max(} amps)	17.1	17.1	DC current through the modules at DT _{max}		
Q _{Cmax} (Watts)	360.1	387.7	Cooling capacity at cold side of the module under DT=0 °C		
AC resistance(ohms)	1.45	1.56	The module resistance is tested under AC		
Tolerance (%)	± 10		For thermal and electricity parameters		

Geometric Characteristics Dimensions in millimeters



Ordering Option

Suffix	Thickness	Flatness/	Lead wire length(mm)		
	(mm)	Parallelism (mm)	Standard/Optional length		
TF	0:4.0±0.1	0:0.1/0.1	125±3/Specify		
TF	1:4.0±0.05	1:0.05/0.05	125±3/Specify		
Eg. TF01: Thickness 4.0 ± 0.1 (mm) and Flatness $0.05/0.05$ (mm)					

Manufacturing Options C. Ceramics:

- 1. T100: BiSn (Tmelt=138°C)
- 2. T200: CuSn (Tmelt = 227 °C)

B. Sealant:

A. Solder:

- 1. NS: No sealing (Standard)
- 2. SS: Silicone sealant
- 3. EPS: Epoxy sealant
- 4. Customer specify sealing

Naming for the Module

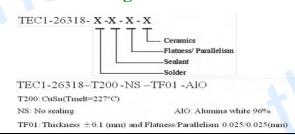
1. Alumina (Al₂O₃, white 96%)

D. Ceramics Surface Options:

1. Blank ceramics (not metallized)

2. Aluminum Nitride (AlN)

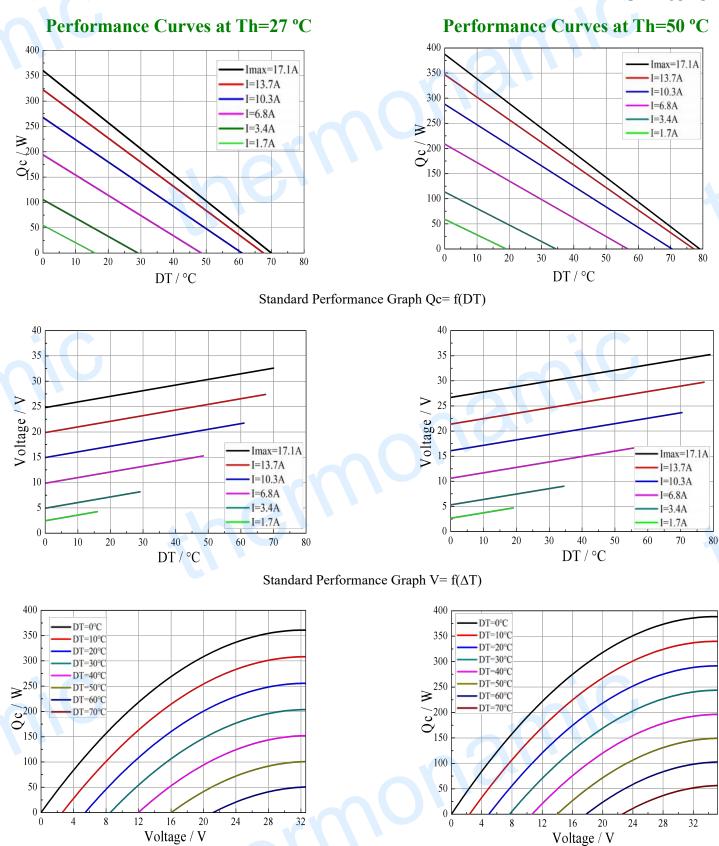
2. Metallized (Au plating)



Creative technology with fine manufacturing processes provides you the reliable and quality products Tel: +86-791-88198288 Fax: +86-791-88198308 Email: <u>sales@thermonamic.com.cn</u> Web Site: www.thermonamic.com.cn

Specification of Thermoelectric Module

TEC1-26318



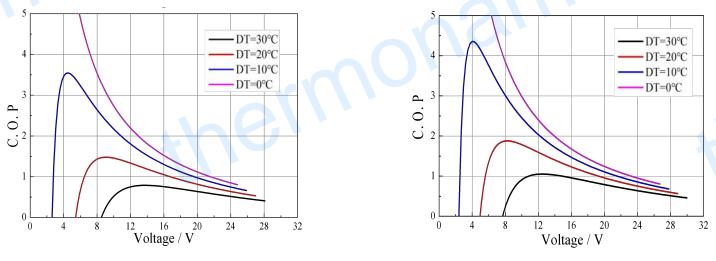
Standard Performance Graph Qc = f(V)

Specification of Thermoelectric Module

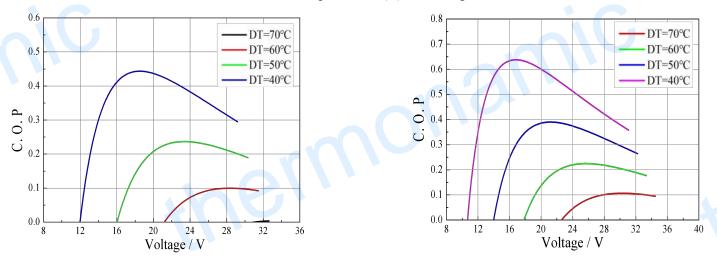
TEC1-26318

Performance Curves at Th=27 °C

Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Susanc • Attach the hot side of module to a heat radiator for heat dissipating.
- Operation or storage module below 100 °C
- Operation below I_{max} or V_{max}
- Work under DC